

Trans IGBT Chip N-CH 650V 216A 714mW Automotive 9-Pin SMIT T/R



Images are for reference only

[Inquiry](#)

Manufacturer: [STMicroelectronics, Inc](#)

Package/Case: ACEPACKSMIT

Product Type: Thyristors

RoHS: RoHS Compliant/Lead free 

Lifecycle: Active

General Description

This device is an IGBT developed using an advanced proprietary trench gate field-stop structure. The device is part of the M series IGBTs, which represent an optimal balance between inverter system performance and efficiency where the low-loss and the short-circuit functionality is essential. Furthermore, the positive $V_{CE(sat)}$ temperature coefficient and the tight parameter distribution result in safer paralleling operation. Thanks to the DBC substrate, the ACEPACK SMIT surface mounting power package offers a low thermal resistance coupled with a electrical isolated top side thermal pad.

Key Features

AEC-Q101 qualified

6 μ s of minimum short-circuit withstand time

$V_{CE(sat)} = 1.65$ V (typ.) @ $I_C = 200$ A

Tight parameter distribution

Positive $V_{CE(sat)}$ temperature coefficient

Low thermal resistance

Maximum junction temperature: $T_J = 175$ °C

Dice on direct bond copper (DBC) substrate

Isolation rating of 3400 Vrms/min

UL recognition: UL 1557 file E81734

Recommended For You

STGIF5CH60TS-L

STMicroelectronics, Inc
SDIP2B-26

STGIPS10K60A

STMicroelectronics, Inc
SDIP-25L

STP24NF10

STMicroelectronics, Inc
TO-220

STGW30NC120HD

STMicroelectronics, Inc
TO-247

STGIPS20K60

STMicroelectronics, Inc
SDIP-25

STB75NF75LT4

STMicroelectronics, Inc
TO-263

STD20NF06LT4

STMicroelectronics, Inc
TO-252

STGW45HF60WD

STMicroelectronics, Inc
TO-247

STGW19NC60HD

STMicroelectronics, Inc
TO-247

STGW30NC60WD

STMicroelectronics, Inc
TO-247

STGW40H120DF2

STMicroelectronics, Inc
TO-247

STGW40V60DF

STMicroelectronics, Inc
TO-247

STGB10NC60HD

STMicroelectronics, Inc
D2PAK

STGB30V60DF

STMicroelectronics, Inc
TO-263

STGP30H60DF

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TO-220